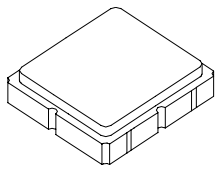
SF2204E

1900 MHz SAW Filter

- ***Low-loss SAW Filter***
- ***Surface-mount 3.0 x 3.0 x 1.4 mm Package***
- ***Complies with Directive 2002/95/EC (RoHS)***



SM3030-6

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-20 to +70	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	F_C			1900		MHz
Insertion Loss, 1880 to 1920 MHz	IL			2.7	3.5	dB
Amplitude Ripple, 1880 to 1920 MHz				1.0	1.5	dB_{P-P}
Group Delay Ripple, 1880 to 1920 MHz				10	40	ns_{P-P}
Input VSWR, 1880 to 1920 MHz				1.5:1	2.0:1	
Output VSWR, 1880 to 1920 MHz				1.5:1	2.0:1	
Attenuation Referenced to 0 dB						
0.3 to 1000 MHz			30	35		dB
1000 to 1700 MHz			30	35		
1700 to 1830 MHz			32	38		
1970 to 2400 MHz			38	45		
2400 to 3000 MHz			30	40		
3000 to 4000 MHz			25	34		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	936, YWWS
Standard Reel Quantity Reel Size 7 Inch	500 Pieces/Reel
Reel Size 13 Inch	3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Input	5
Output	2
Ground	All Others

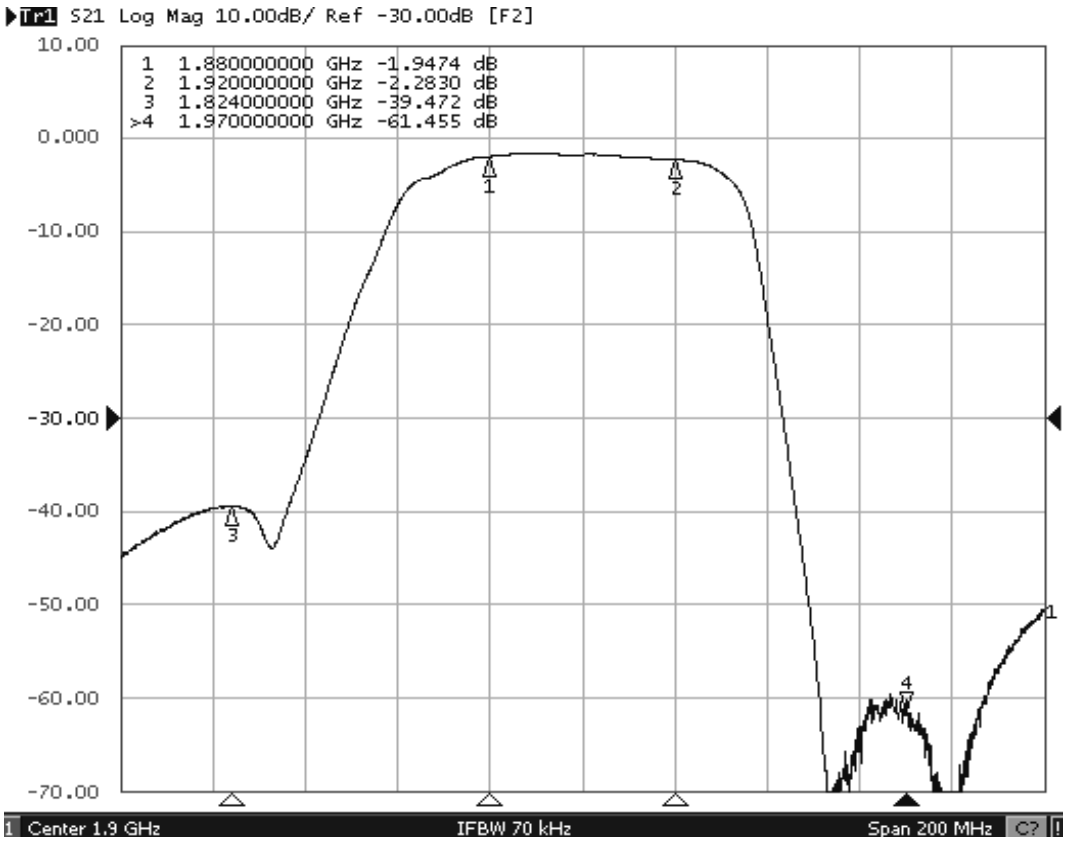
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

Notes:

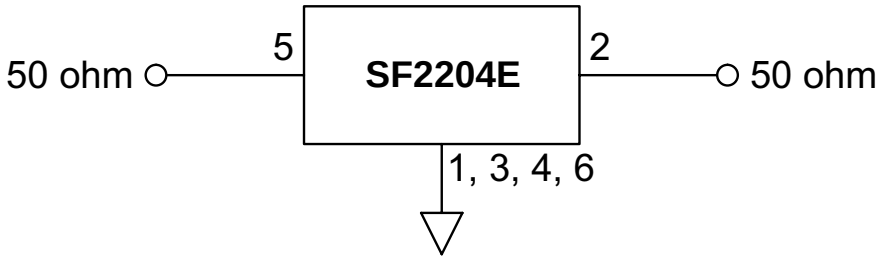
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc

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Filter Passband Response, 1800 to 2000 MHz

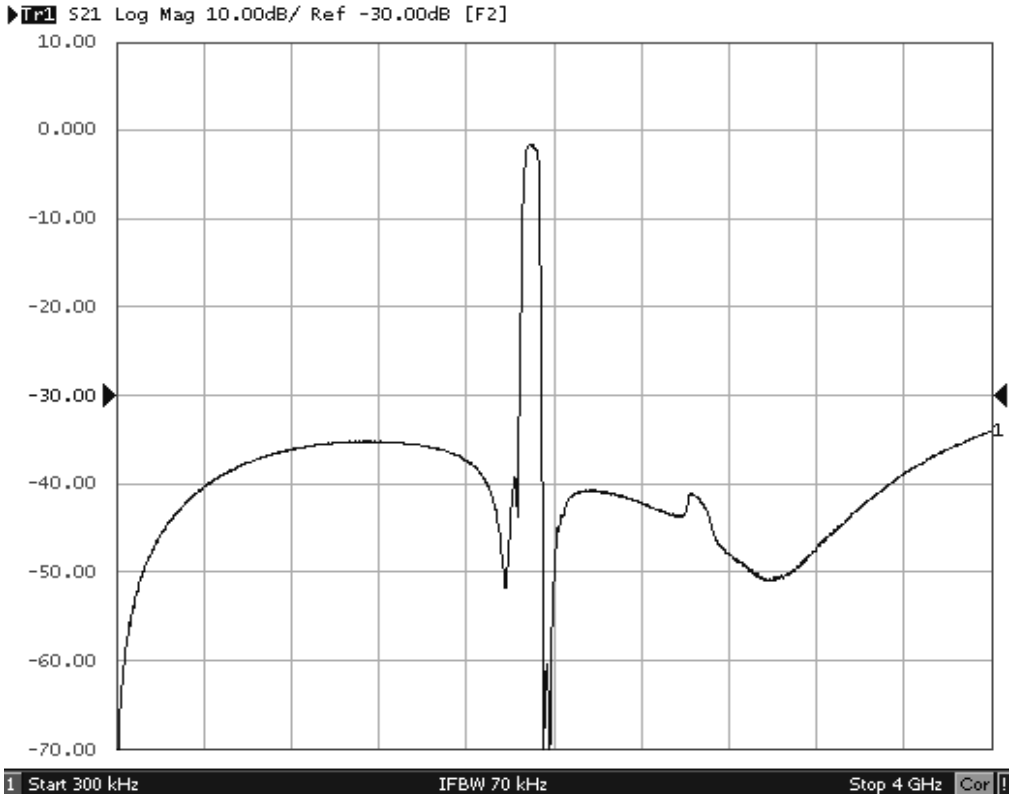


Filter Test Circuit

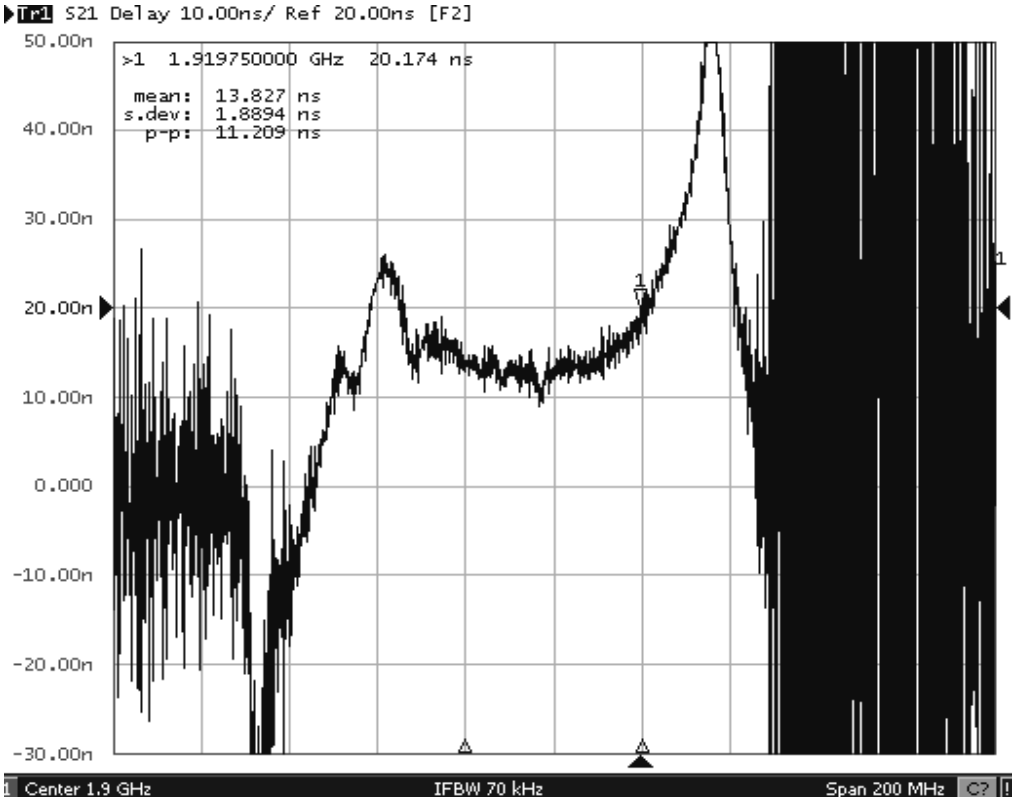


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Filter Broadband Response, 300 kHz to 4000 MHz

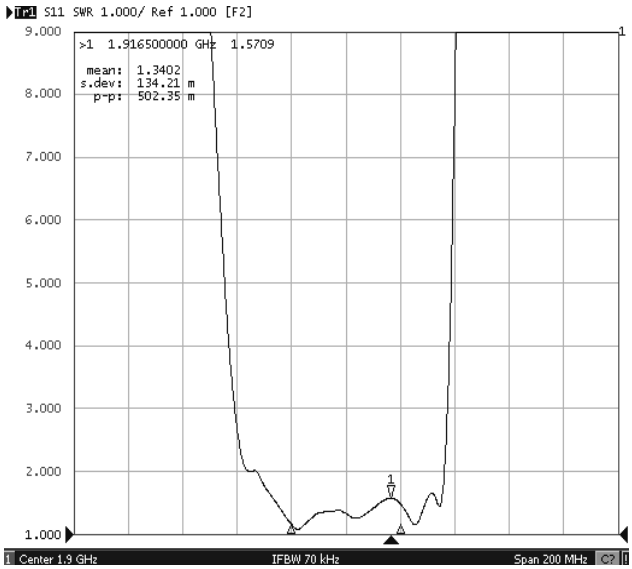


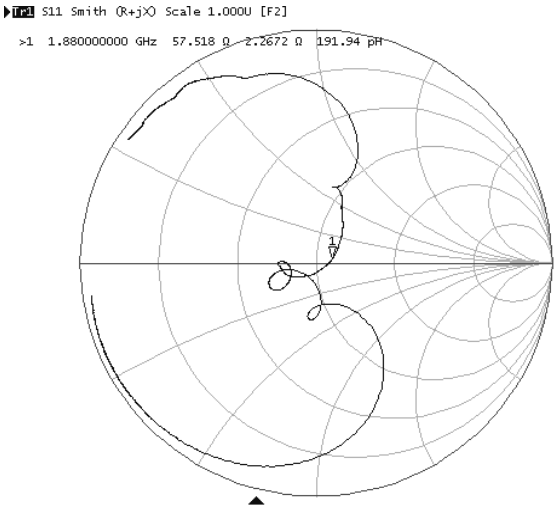
Filter Group Delay Plot, 1800 to 2000 MHz

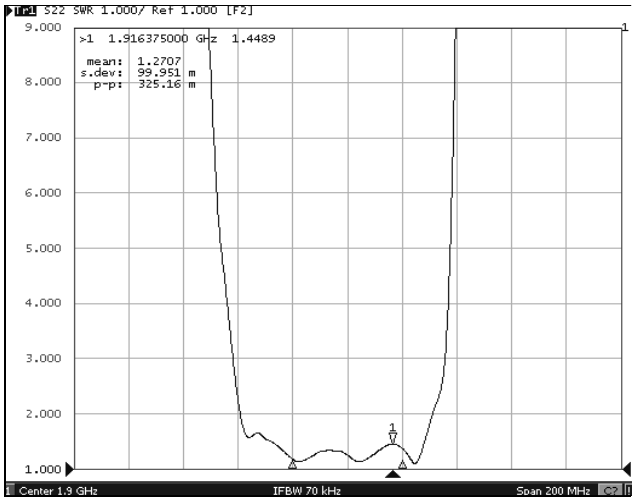


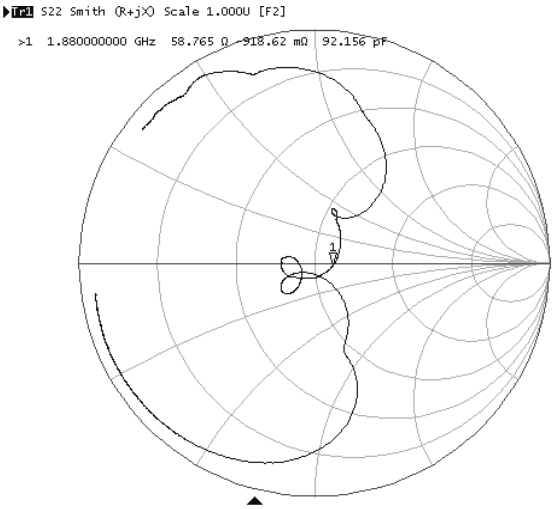
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Input and Output VSWR Plots





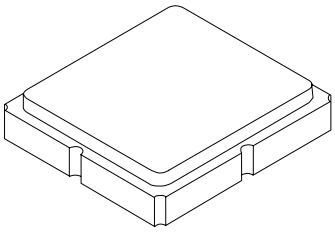


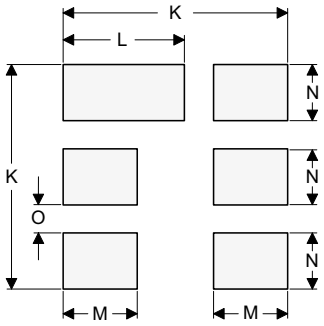


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SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case
3.0 X 3.0 mm Nominal Footprint





PCB Footprint Top View

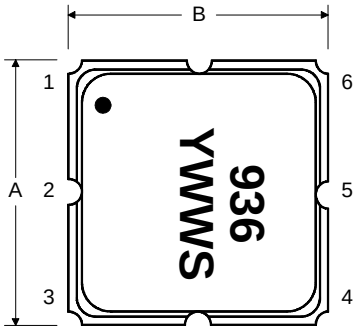
Case and PCB Footprint Dimensions

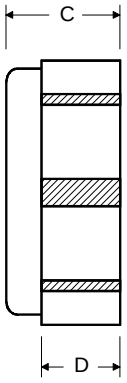
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

Case Materials

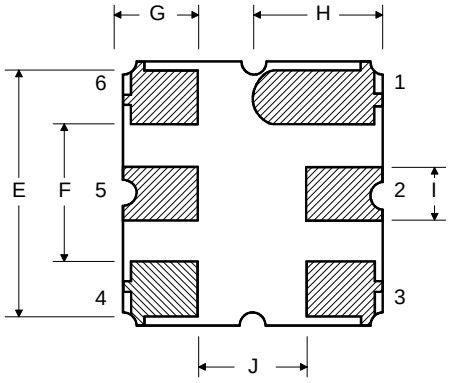
Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

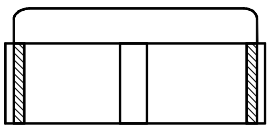
TOP VIEW





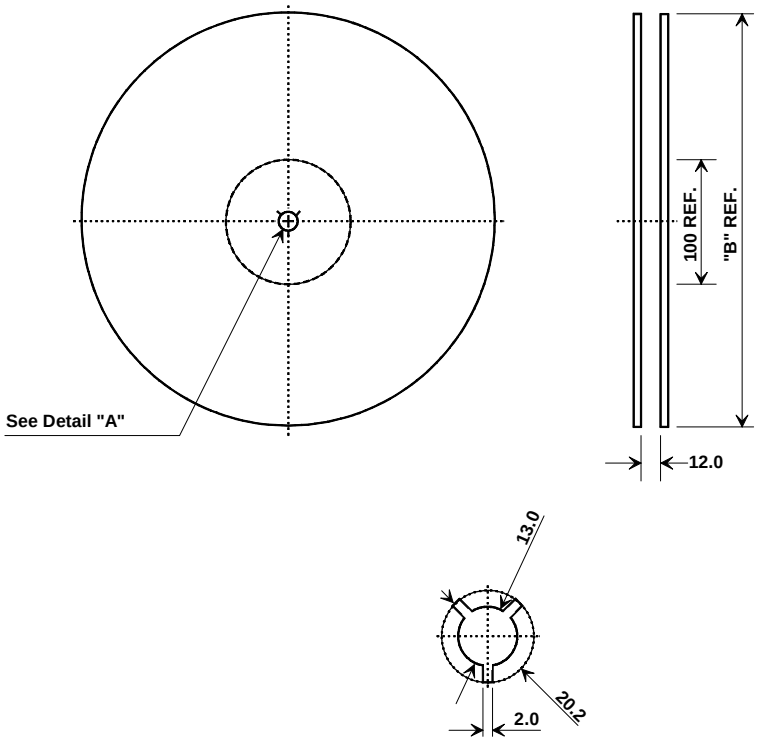
BOTTOM VIEW





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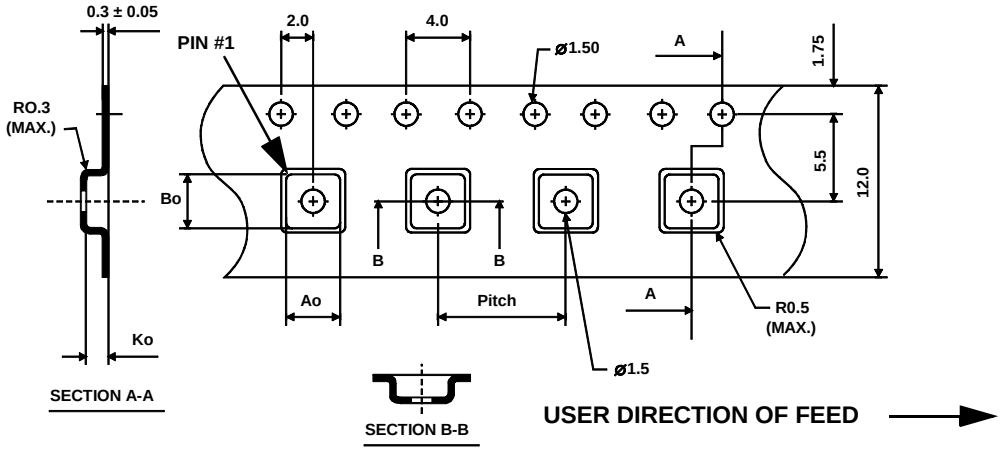
Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

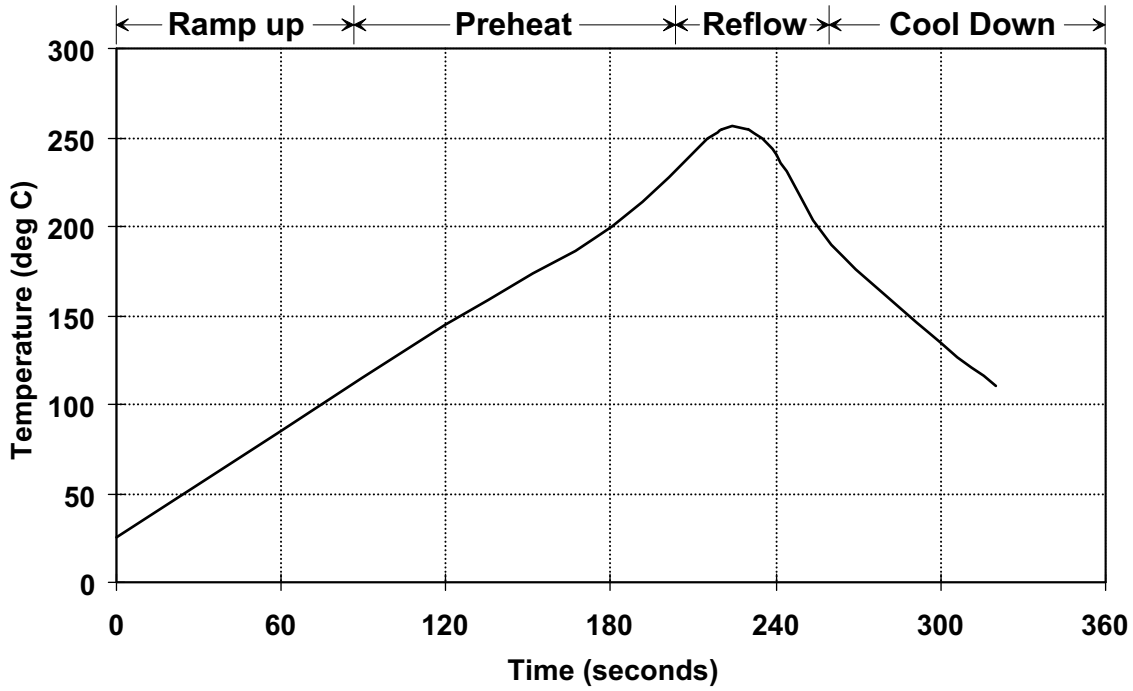
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



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Typical Solder Reflow Profile



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